

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
29 January 2004 (29.01.2004)

PCT

(10) International Publication Number
WO 2004/010472 A2

(51) International Patent Classification⁷: **H01L**

(21) International Application Number:
PCT/US2003/022389

(22) International Filing Date: 18 July 2003 (18.07.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/397,082 19 July 2002 (19.07.2002) US

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(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *without international search report and to be republished upon receipt of that report*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.



WO 2004/010472 A2

(54) Title: PROCESS FOR FABRICATING, AND LIGHT EMITTING DEVICE RESULTING FROM, A HOMOGENOUSLY MIXED POWDER/PELLETIZED COMPOUND

(57) Abstract: The present invention comprises a process of mixing a luminous substance in powder form to a transferable grade molding compound in a pelletized or powder form, such as a clear epoxy, to derive a homogeneous mixture that can be pressed and sintered into solid pellets. The solid pellets are further processed so as to permit their deposition on and around a light emitting semiconductor driver so as to obtain a white light emitting semiconductor device. This white light emitting device can be used in a variety of lighting applications.

5 **PROCESS FOR FABRICATING, AND LIGHT EMITTING DEVICE
 RESULTING FROM, A HOMOGENOUSLY MIXED
 POWDER/PELLETIZED COMPOUND**

CROSS REFERENCE TO RELATED APPLICATION

10 This application is related to U.S. provisional patent application No.
60/397,082, filed July 19, 2002, entitled PROCESS FOR PREPARING, AND
DEVICE RESULTING FROM, A HOMOGENOUSLY MIXED
POWDER/PELLETIZED COMPOUND FOR USE IN LIGHT EMITTING
SEMICONDUCTOR DEVICES, the entire contents of which are incorporated
15 herein by this reference. The Applicants hereby claim the benefits of this earlier
pending provisional application under 35 U.S.C. Section 119(e).

TECHNICAL FIELD OF THE INVENTION

20 The present invention relates to processes for preparing compositions
used in the fabrication of light emitting semiconductor devices, and also relates to
the devices resulting from the use of said process.

BACKGROUND OF THE INVENTION

25 LEDs are used in a variety of applications, such as displays, illumination
in control panels, in traffic lights and electronic devices. An LED is a
semiconductor device that converts electrical energy into optical energy. This
occurs when a forward bias is applied to the device, resulting in holes in the P-
30 type semiconductor material combining with the electrons in the N-type
semiconductor material at the P-N junction. A "white" light emitting diode uses a
blue light emitting diode as the source of the light. A luminous material layered

over the blue light emitting diode acts to partly absorb the blue light and convert it into yellow or yellowish green light. When mixed, the blue and yellow/yellowish green light combine as white light.

A conventional method of producing white light emitting devices includes a process in which yttrium aluminate (“YAG”) is directly deposited onto a light emitting diode (“LED”) chip surface in order to produce LEDs that emit white light. However, a disadvantage of said process, and the resulting LED, is that the color temperature from such a white LED is not uniform over a plurality of angular positions due to the non-uniform thickness of the YAG over the LED chip surface. Further, this unequal distribution of color temperature occurs on a device by device basis within the same lot.

In addition, at elevated drive current, bleed-through of radiation in the ultra-violet (“UV”) range can occur. The use of the conventional process in producing these “white” light emitting devices disadvantageously results in package complexity, leading to limited ruggedness and decreased reliability of the devices.

SUMMARY OF THE INVENTION

The present invention comprises a process of mixing a luminous substance in powder form to a transferable grade molding compound in a pelletized or powder form, such as a clear epoxy, to derive a homogeneous mixture that can be pressed and sintered into solid pellets. The solid pellets are further processed so as to permit their deposition on and around a light emitting semiconductor driver so as to obtain a “white” light emitting semiconductor device. This “white” light emitting device can be used in a variety of lighting applications.

DETAILED DESCRIPTION OF THE DISCLOSED PROCESS AND DEVICE

The present invention discloses a process for adding a luminous substance in powder form to a transferable grade molding compound in pellet or powder form to derive a homogeneous mixture that can be pressed and sintered into pellets so as to obtain a “white” light emitting semiconductor device.

5 In an embodiment of the invention, the luminous powdered substance is a Cerium doped garnet, such as the inorganic luminous substance YAG:Ce. In this embodiment, YAG:Ce is homogeneously admixed with a pelletized molding compound, such as a clear epoxy. Although YAG:Ce has an index of refraction of about 1.84, resulting in good mixing of blue diode emissions with
10 yellow/yellowish green converter radiation, any type of luminous substance in powder form can be used in the disclosed process. Other luminous substance powders that can be homogeneously distributed within the molding compound include but are not limited to other garnets doped with rare earths.

The particle sizes of the luminous powdered substances are less than or
15 equal to 5 microns and can be spherical or flake-like in shape. Different chromaticity can be obtained by adjusting the luminous powder’s (i) percentage by weight of the combined material and (ii) micron size, before admixing and pelletizing. Because of the characteristics of the mixture, no sedimentation of the substance occurs and the mixture remains homogeneous. The powder and pellets
20 must be stored in Nitrogen before and during production as they are susceptible to moisture. Because the luminous powder added to the epoxy changes its spiral flow, the transfer pressure must be increased 10% to 15% of manufacturer’s recommended settings. As used with the Microsemi(r) PM3 package, a “color tunable” device can be produced. The disclosed process can also be used to
25 convert the wavelength of blue, green or ultra-violet light of LEDs to other wavelengths.

By providing uniformity in concentration by weight and homogeneous disposition of the luminous substance within the molding compound, uniform distribution of color temperature can be achieved. Using the disclosed process to
30 control the percentage weight of the luminous substance, such as YAG, to the molding compound, such as a clear epoxy, ensures uniform distribution of color

temperature. Furthermore, use of the disclosed process allows a more robust injection molded package. This is accomplished by depositing the admixed substance around the LED chip atop a copper lead frame. Specifically, pellets are taken from a freezer and stored in Nitrogen until they reached room temperature.

- 5 They are then removed from the Nitrogen box and placed in a feed bowl to be loaded into a mold shuttle for transfer. The feed bowl and mold shuttle are purged with nitrogen to keep the pellets dry. The use of this process advantageously results in no UV bleed through at elevated drive current.

More specifically, the powder/pelletized composition includes, among
10 other things, the following parts:

- (a) molding compound, such as a clear epoxy;
- (b) luminous substances, such as YAG:Ce;
- (c) thixotropic agent, such as pyrogenic silicic acid, to thicken the epoxy casting resin;
- 15 (d) mineral diffuser, such as CaF₂, for optimizing the luminous pattern of the composition;
- (e) processing adjuvant, such as glycol ether or surface modifiers based on silicone, to improve the compatibility between the epoxy and the luminous substance;
- 20 (f) hydrophobic agent, such as liquid silicone wax to modify the pigment surface; and
- (g) adhesion promoters, to improve the adhesion between the pigments and the epoxy.

The innovative teachings of the present invention are described with
25 particular reference to the disclosed embodiment. However, it should be understood that the embodiment provides only one example of the many advantageous uses and innovative teachings herein. Various alterations, modifications and substitutions can be made to the disclosed invention without departing in any way from the spirit and scope of the invention.

CLAIMS

What is claimed is:

1. A light emitting device package, comprising:
a semiconductor junction operable to emit light when biased;
an homogenous composition deposited on the semiconductor junction adapted to filter and combine predetermined wavelengths of light from the semiconductor surface.
2. The light emitting device package of Claim 1, the homogenous composition further comprising a sintered and pelletized mixture of a molding compound and a luminous substance.
3. The light emitting device package of Claim 2, wherein the molding compound is in pelletized form prior to sintering and pelletization.
4. The light emitting device package of Claim 3, the pelletized molding compound further comprising a clear epoxy.
5. The light emitting device package of Claim 2, wherein the luminous substance is in powder form prior to sintering and pelletization.
6. The light emitting device package of Claim 5, wherein the luminous powder is less than or equal to 5 microns in size prior to sintering and pelletization.
7. The light emitting device package of Claim 6, wherein the luminous powder is spherical or flake-like in shape prior to sintering and pelletization.
8. The light emitting device package of Claim 2, the molding compound further comprising a clear epoxy.
9. The light emitting device package of Claim 8, the clear epoxy further incorporating a thixotropic agent to thicken the epoxy casting resin.
10. The light emitting device package of Claim 2, the luminous substance further comprising a Cerium doped garnet.
11. The light emitting device package of Claim 2, the luminous substance further comprising YAG:Ce.

12. The light emitting device package of Claim 2, the luminous substance having admixed a predetermined amount of mineral diffuser so as to optimize the luminous pattern of the composition.

13. The light emitting device package of Claim 12, the mineral diffuser comprising CaF₂.

14. The light emitting device package of Claim 2, the molding compound and luminous substance composition further including a processing adjuvant.

15. The light emitting device package of Claim 2, further comprising a predetermined chromaticity of light based on the luminous powder's percentage by weight of the composition and micron size, before admixing and pelletizing.

16. A method of fabricating a light emitting device, comprising:
admixing a luminous substance to a transferable grade molding compound to derive a homogeneous mixture;
pressing and sintering the homogeneous mixture into solid pellets;
processing the solid pellets for application on a semiconductor surface;
and
depositing the processed solid pellets on the semiconductor surface.

17. The method of fabricating a light emitting device of Claim 16 wherein the molding compound is in a pelletized form prior to pressing and sintering the homogeneous mixture into solid pellets.

18. The method of fabricating a light emitting device of Claim 16 wherein the pelletized molding compound further comprises a clear epoxy.

19. The method of fabricating a light emitting device of Claim 16 wherein the molding compound is in a powdered form prior to pressing and sintering the homogeneous mixture into solid pellets.

20. The method of fabricating a light emitting device of Claim 19 wherein the powdered molding compound further comprises a clear epoxy.

21. The method of fabricating a light emitting device of Claim 16 wherein the luminous substance is in powdered form prior to pressing and sintering the homogeneous mixture into solid pellets.

22. The method of fabricating a light emitting device of Claim 16 wherein the light emitted by the light emitting device comprises a white light.

23. A method of fabricating a light emitting chip comprising depositing an admixed substance of epoxy and a luminous substance around an LED chip located on a copper lead frame.